



Application Data Sheet  
Application Information

Application type::	Regular
Subject matter::	Utility
CD-ROM or CD-R::	None
Number of CD disks::	0
Number of copies of CDs::	0
Sequence submission?::	No
Computer readable form (CRF)?::	No
Number of copies of CRF::	0
Title::	Flip Chip Package With Reinforced Bumps
Attorney docket number::	WANG3232/EM
Request for early publication?::	No
Request for non-publication?::	No
Suggested drawing figure::	2
Total drawing sheets::	2
Small entity?::	No

Applicant Information

Applicant authority type::	Inventor
Primary citizenship country::	Taiwan, R.O.C.
Status:	Full capacity
Given name::	Sung-Fei
Middle name::	
Family name::	WANG
City of Residence::	Kaohsiung
Country of residence::	Taiwan, R.O.C.

Street of mailing address:: No. 21, Alley 90, Lane 729,  
Jiachang Rd., Nantz Chiu  
City of mailing address:: Kaohsiung  
Country of mailing address:: Taiwan, R.O.C.  
Postal or zip code of mailing  
address::

Correspondence Information

Correspondence customer number:: 23364  
Phone number:: 703-683-0500  
Fax number:: 703-683-1080  
E-mail address:: mail@baconthomas.com

Representative Information

Representative customer number:: 23364

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority claimed::
Taiwan, R.O.C.	092109531	<u>04/23/2003</u>	Yes

Assignee Information

Assignee name:: Advanced Semiconductor  
Engineering, Inc.  
Street of mailing address:: 26 Chin 3<sup>rd</sup> Rd., Nantze Export  
Processing Zone  
City of mailing address:: Kaohsiung  
Country of mailing address:: Taiwan, R.O.C.  
Postal or zip code of  
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